



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Micro Commercial Components



Micro Commercial Components
 20736 Marilla Street Chatsworth
 CA 91311
 Phone: (818) 701-4933
 Fax: (818) 701-4939

MT200CB08T2
MT200CB12T2
MT200CB16T2
MT200CB18T2

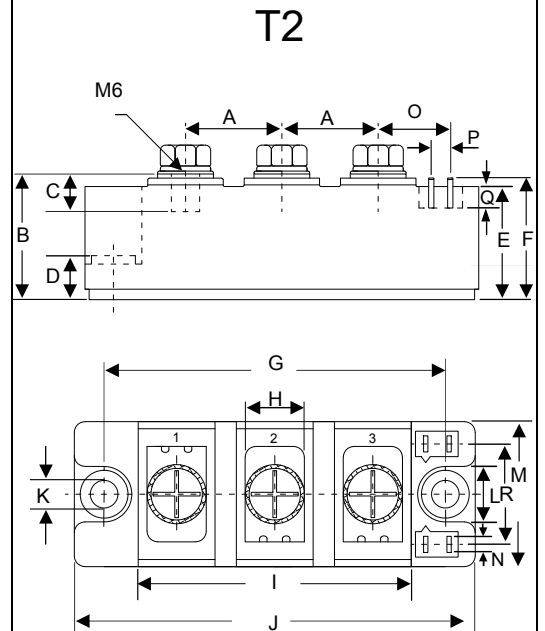
200 Amp
THYRISTOR/DIODE
MODULE
800~1800 Volts

Features

- Lead Free Finish/RoHS Compliant (NOTE 1) ("P" Suffix designates RoHS Compliant. See ordering information)
- International standard package
- Heat transfer through aluminum oxide DBC ceramic isolated metal baseplate
- Glass passivated chip
- Simple Mounting

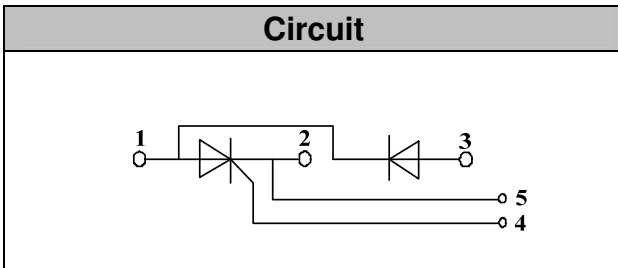
Applications

- Power Converters
- Lighting Control
- DC Motor Control and Drives
- Heat and temperature control



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	.894	.917	22.70	23.30	
B	1.169	1.193	29.70	30.30	
C	.343	.366	8.70	9.30	
D	.323	.343	8.20	8.70	
E	1.051	1.075	26.70	27.30	
F	1.130	1.154	28.70	29.30	
G	.120	.130	79.70	80.30	
H	.500	.524	12.70	13.30	
I	2.501	2.531	63.70	64.30	
J	3.689	3.713	93.70	94.30	
K	.256		6.50		∅
L	.500	.524	12.70	13.30	
M	1.327	1.350	33.70	34.30	
N	0.032X0.11		0.8X2.8		
O	.677	.700	17.20	17.80	
P	.185	.209	4.70	5.30	
Q	.185	.209	4.70	5.30	
R	.902	.925	22.90	23.50	

Circuit



Module Type

TYPE	VRRM/VDRM	VRSM
MT200CB08T2	800V	900V
MT200CB12T2	1200V	1300V
MT200CB16T2	1600V	1700V
MT200CB18T2	1800V	1900V

◆ Diode

Maximum Ratings

Symbol	Item	Conditions	Values	Units
I _D	Output Current(D.C.)	T _c =85°C	200	A
I _{FSM}	Surge forward current	t=10mS T _{vj} =45°C	6800	A
i ² t	Circuit Fusing Consideration		231200	A ² s
Visol	Isolation Breakdown Voltage(R.M.S)	a.c.50HZ;r.m.s.;1min	3000	V
T _{vj}	Operating Junction Temperature		-40 to +125	°C
T _{stg}	Storage Temperature		-40 to +125	°C
M _t	Mounting Torque	To terminals(M6)	3±15%	Nm
M _s		To heatsink(M6)	5±15%	Nm
Weight	Module (Approximately)		165	g

Thermal Characteristics

Symbol	Item	Conditions	Values	Units
R _{th(j-c)}	Thermal Impedance, max.	Junction to Case	0.08	°C/W
R _{th(c-s)}	Thermal Impedance, max.	Case to Heatsink	0.05	°C/W

Electrical Characteristics

Symbol	Item	Conditions	Values			Units
			Min.	Typ.	Max.	
V _{FM}	Forward Voltage Drop, max.	T=25°C I _F =620A			1.70	V
I _{RRM}	Repetitive Peak Reverse Current, max.	T _{vj} =25°C V _{RD} =V _{RRM} T _{vj} =125°C V _{RD} =V _{RRM}		≤0.5 ≤9		mA mA

◆ Thyristor
Maximum Ratings

Symbol	Item	Conditions	Values	Units
I_{TAV}	Average On-State Current	Sine 180°; $T_C=85^\circ\text{C}$	200	A
I_{TSM}	Surge On-State Current	$T_{VJ}=45^\circ\text{C}$ t=10ms, sine $T_{VJ}=125^\circ\text{C}$ t=10ms, sine	5500 5000	A
i^2t	Circuit Fusing Consideration	$T_{VJ}=45^\circ\text{C}$ t=10ms, sine $T_{VJ}=125^\circ\text{C}$ t=10ms, sine	151000 125000	A2s
Visol	Isolation Breakdown Voltage(R.M.S)	a.c.50HZ;r.m.s.;1min	3000	V
T_{vj}	Operating Junction Temperature		-40 to +130	°C
T_{stg}	Storage Temperature		-40 to +125	°C
M_t	Mounting Torque	To terminals(M6)	$3 \pm 15\%$	Nm
M_s		To heatsink(M6)	$5 \pm 15\%$	Nm
di/dt	Critical Rate of Rise of On-State Current	$T_{VJ}=T_{VJM}$, $2/3V_{DRM}$, $I_G=500\text{mA}$ $T_r < 0.5\mu\text{s}$, $t_p > 6\mu\text{s}$	200	A/us
dv/dt	Critical Rate of Rise of Off-State Voltage, min.	$T_J=T_{VJM}$, $2/3V_{DRM}$ linear voltage rise	1000	V/us
a	Maximum allowable acceleration		50	m/s^2

Thermal Characteristics

Symbol	Item	Conditions	Values	Units
$R_{th(j-c)}$	Thermal Impedance, max.	Junction to Case	0.16	°C/W
$R_{th(c-s)}$	Thermal Impedance, max.	Case to Heatsink	0.10	°C/W

Electrical Characteristics

Symbol	Item	Conditions	Values		Units
V_{TM}	Peak On-State Voltage, max.	$T=25^\circ\text{C}$ $I_T=620\text{A}$		1.70	V
I_{RRM}/I_{DRM}	Repetitive Peak Reverse Current, max. / Repetitive Peak Off-State Current, max.	$T_{VJ}=T_{VJM}$, $V_R=V_{RRM}$, $V_D=V_{DRM}$		40	mA
V_{TO}	On state threshold voltage	For power-loss calculations only ($T_{VJ}=125^\circ\text{C}$)		0.85	V
r_T	Value of on-state slope resistance. max	$T_{VJ}=T_{VJM}$		1.5	mΩ
V_{GT}	Gate Trigger Voltage, max.	$T_{VJ}=25^\circ\text{C}$, $V_D=6\text{V}$		3	V
I_{GT}	Gate Trigger Current, max.	$T_{VJ}=25^\circ\text{C}$, $V_D=6\text{V}$		200	mA
V_{GD}	Non-triggering gate voltage, max.	$T_{VJ}=125^\circ\text{C}$, $V_D=2/3V_{DRM}$		0.25	V
I_{GD}	Non-triggering gate current, max.	$T_{VJ}=125^\circ\text{C}$, $V_D=2/3V_{DRM}$		10	mA
I_L	Latching current, max.	$T_{VJ}=25^\circ\text{C}$, $R_G=33\Omega$	300	1000	mA
I_H	Holding current, max.	$T_{VJ}=25^\circ\text{C}$, $V_D=6\text{V}$	150	400	mA
tgd	Gate controlled delay time	$T_{VJ}=25^\circ\text{C}$, $I_G=1\text{A}$, $di_G/dt=1\text{A/us}$	1		us
tq	Circuit commutated turn-off time	$T_{VJ}=T_{VJM}$	100		us

Performance Curves

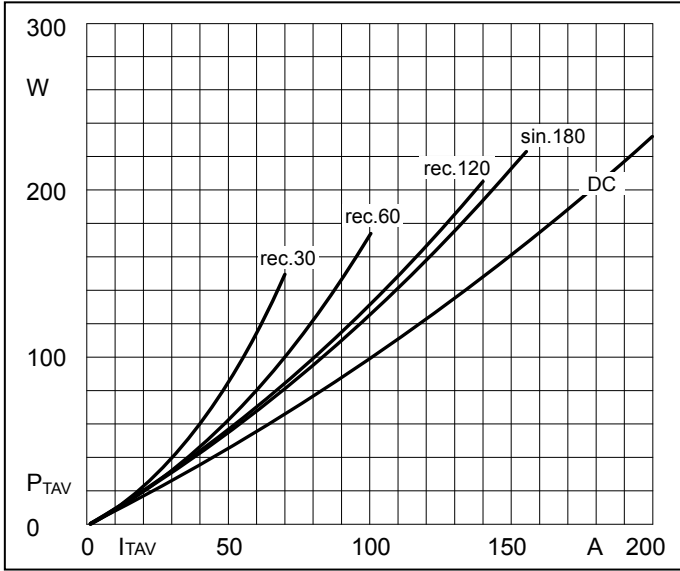


Fig1. Power dissipation

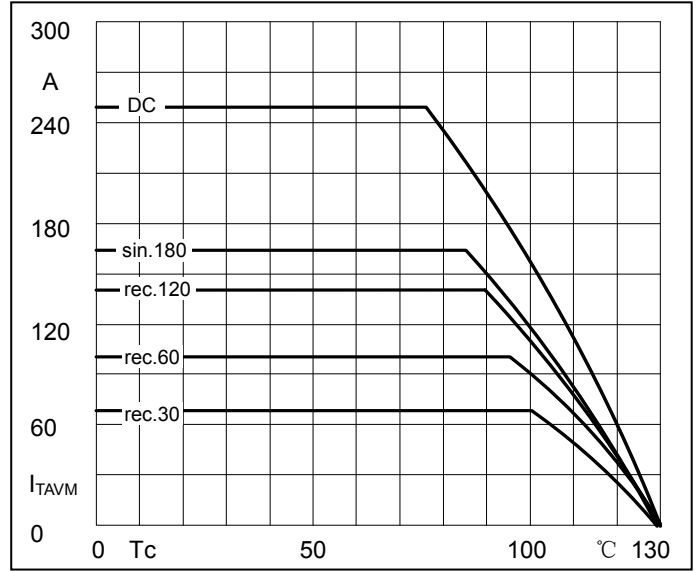


Fig2. Forward Current Derating Curve

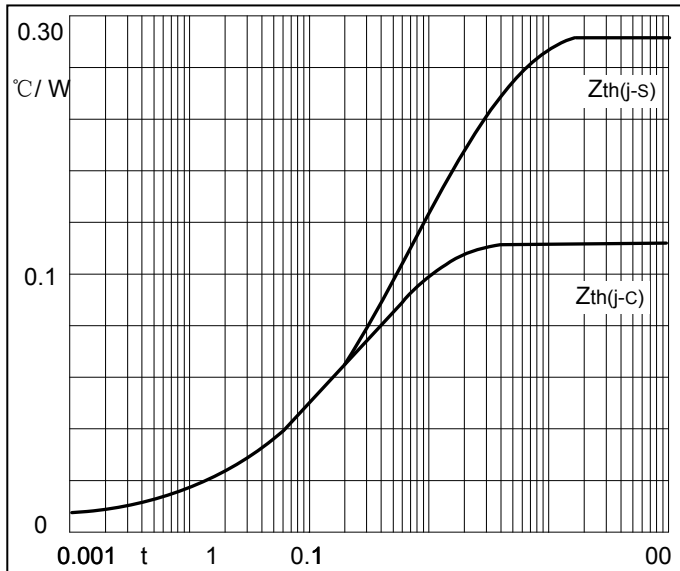


Fig3. Transient thermal impedance

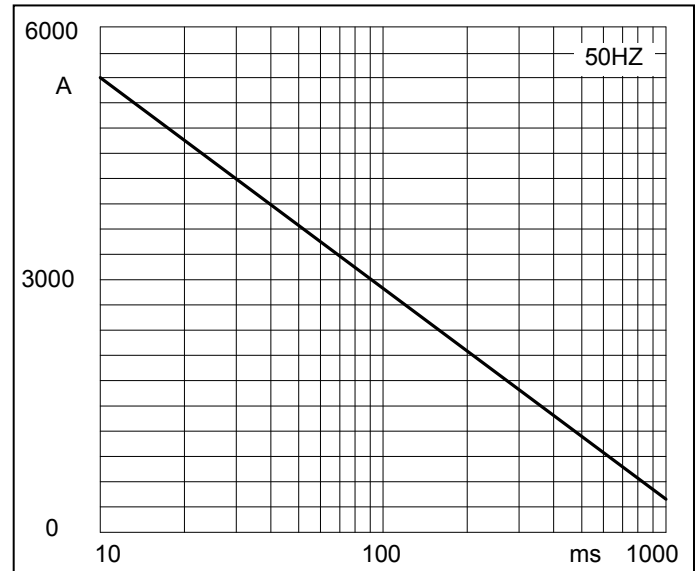


Fig4. Max Non-Repetitive Forward Surge Current

Performance Curves

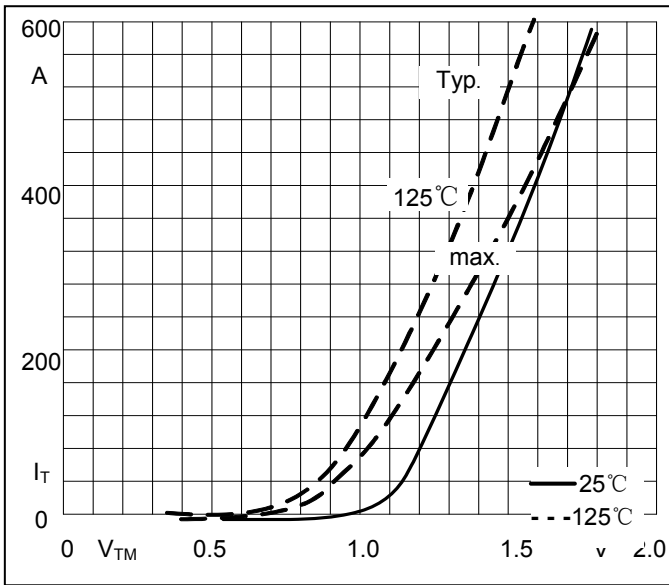


Fig5. Forward Characteristics

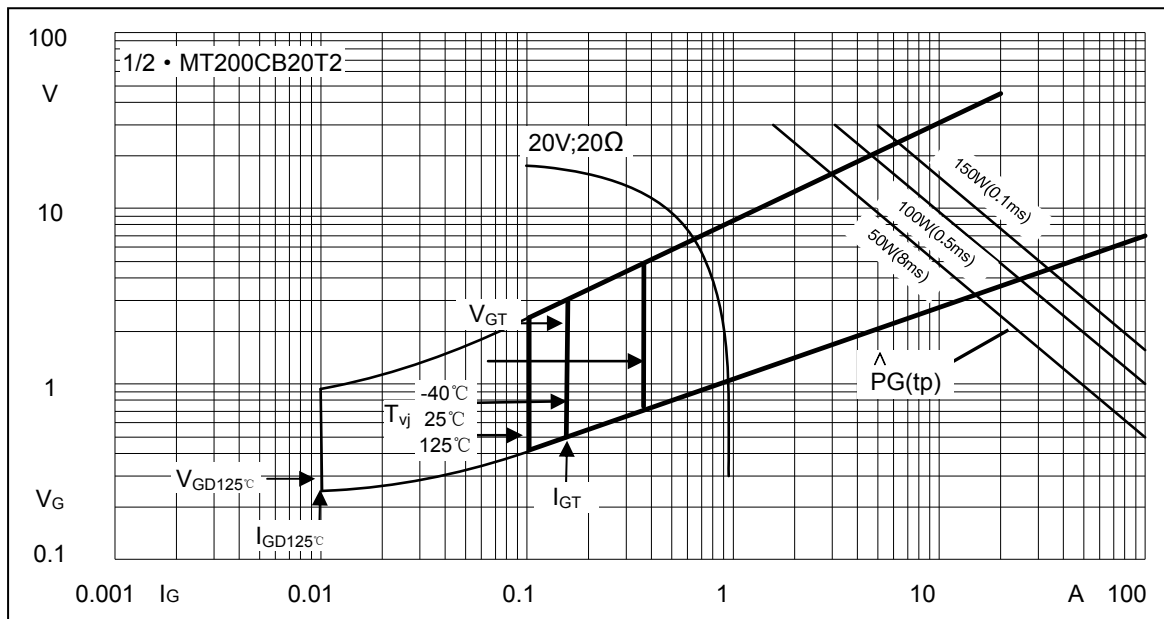


Fig6. Gate trigger Characteristics



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Ordering Information :

Device	Packing
Part Number-BP	Bulk: 8PCS/BOX ;80PCS/CTN

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